

THIS SHEET HAS BEEN
REPLACED

22

INTEGRATED CIRCUIT AND PROCESS FOR ITS MANUFACTURE

ABSTRACT

The invention relates to an integrated circuit device comprising (i) a substrate (2); (ii) metallic circuit lines (4) positioned on the substrate (2) and (iii) a dielectric material (6) positioned on the circuit lines (4). The dielectric material (6) comprises the reaction product of a hyperbranched polymer and organic polysilica.

Fig. 1

This Sheet Has Been Replaced

